

In the Specification:

Please amend the title of the application as follows:

~~PROCESS FOR SELF-ALIGNED MANUFACTURE OF INTEGRATED~~
ELECTRONIC DEVICES

Please insert new paragraph 13 and amend original paragraph 13 (new paragraph 14) as follows:

[13] FIGS. 1 to 4 are cross-sectional views through a semiconductor wafer in successive fabrication steps of a process according to the prior art;

[14] FIGS. ~~4-5~~ to 16 are cross-sectional views through a semiconductor wafer in successive fabrication steps of a process according to a first embodiment of the present invention; and